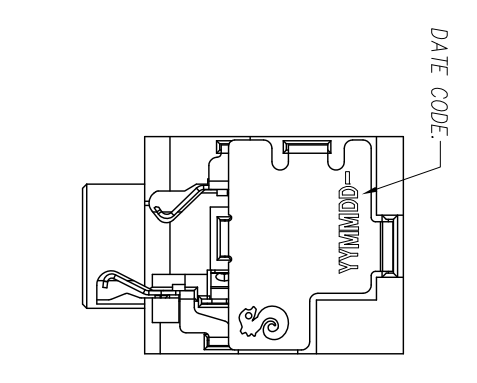
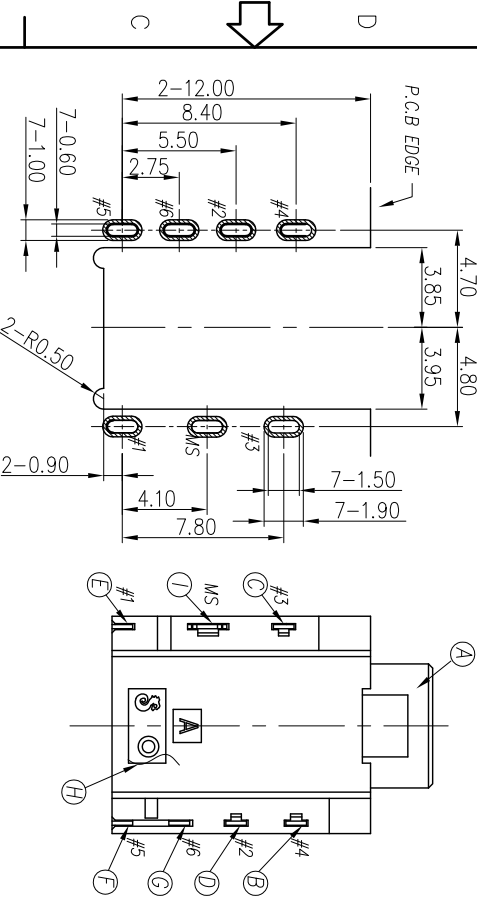
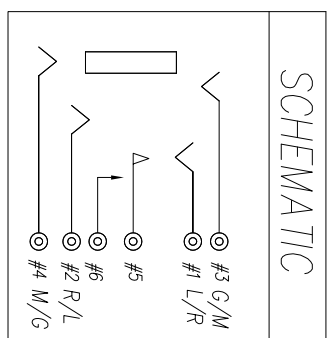
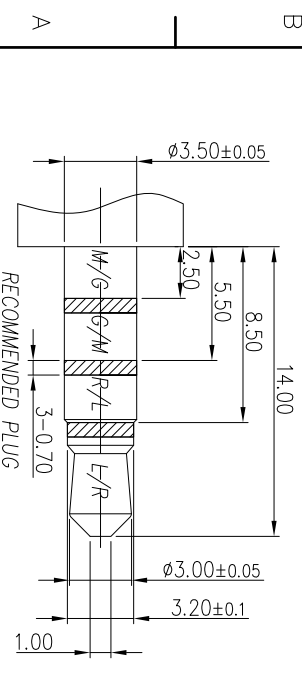


- SPECIFICATIONS:**
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500V DC.
  - CONTACT RESISTANCE: 50mΩ MAX(INITIAL).
  - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
  - LIFE TEST: 5,000 CYCLES.
  - INSERTION FORCE: 0.3-3.0kgf.
  - WITHDRAWAL FORCE: 0.3-3.0 kgf.
  - AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
  - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
  - MARKING: MARK "S" ON TOP OF CONNECTOR.
  - PACKING: TAPE & REEL.
  - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
  - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT.
  - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING.



RECOMMENDED PCB LAYOUT  
TOP VIEW ; TOL.±0.05



SCHEMATIC

I	SHELL	1	COPPER ALLOY, 0.2t	Ni 60% Min.
H	SEPARATOR	1	HIGH TEMP. THERMOPLASTIC UL 94V-0	BLACK
G	MAKE TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA GOLD FLASH ON SOLDER AREA ALL OVER 50μ" Ni.
F	TRANSFER TERMINAL	1	COPPER ALLOY, 0.2t	
E	TIP SPRING	1	COPPER ALLOY, 0.2t	
D	RING A	1	COPPER ALLOY, 0.2t	
C	RING B	1	COPPER ALLOY, 0.2t	
B	EARTH	1	COPPER ALLOY, 0.2t	
A	BODY	1	HIGH TEMP. THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS: ANGLES:				
X	:±0.5	X	:±2°	
X.X	:±0.3	X.X	:±1°	
X.XX	:±0.2			
Singatron Enterprise Co., Ltd. 信譽企業股份有限公司				
TITLE: 3.5Ø PHONE JACK				
DWN	HM-JIANG	PART NO.	2S13080-059111F	
CHKD	BRUCE	SCALE	4:1	UNIT: mm
APVD	TUSSEN	SIZE: A3	SHEET: 1 OF 1	REV: A
CUSTOMER COPY				